

INTEGRATED CIRCUIT PACKAGE TESTING DEVICE AND METHOD

ABSTRACT

5 An integrated circuit (IC) package testing device using a selectable number of leaf springs to provide a resilient and consistent normal force to the IC package and the method of operating the device. The leaf springs are shaped to provide the proper compliance and resilient force and are shaped to fit side-by-side within the lid of the device. The springs can be easily changed for differently sized IC packages.

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